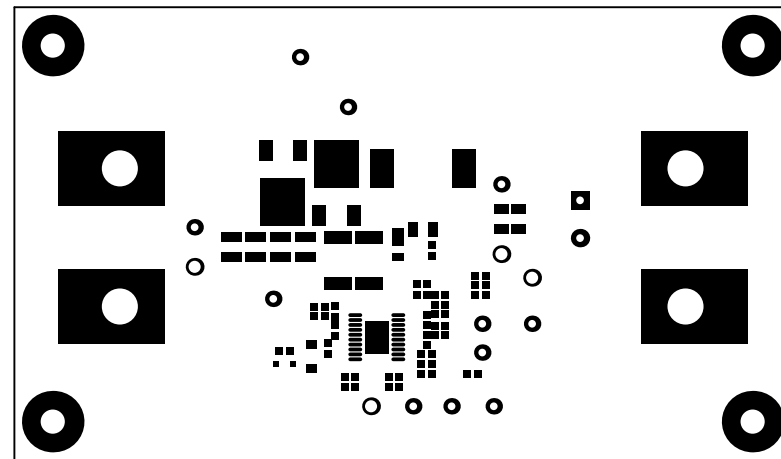
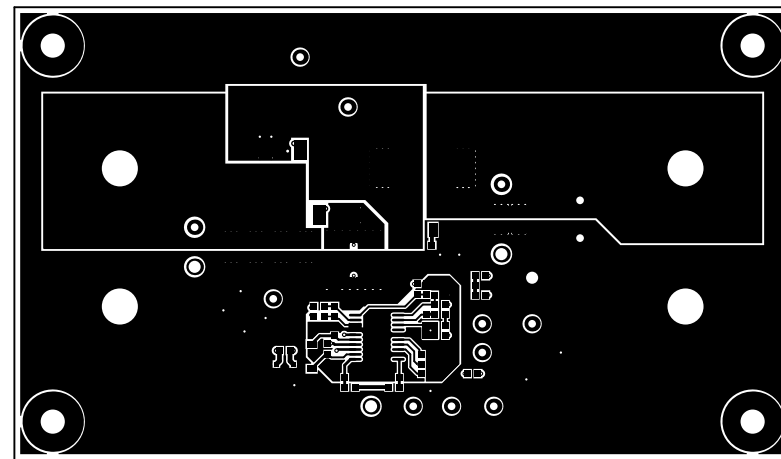


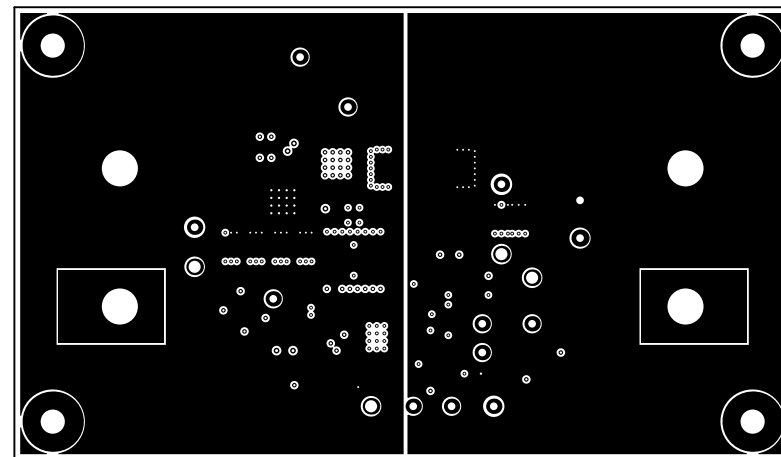
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20808	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 11/30/2017 6:37:50 PM	TEXAS INSTRUMENTS	



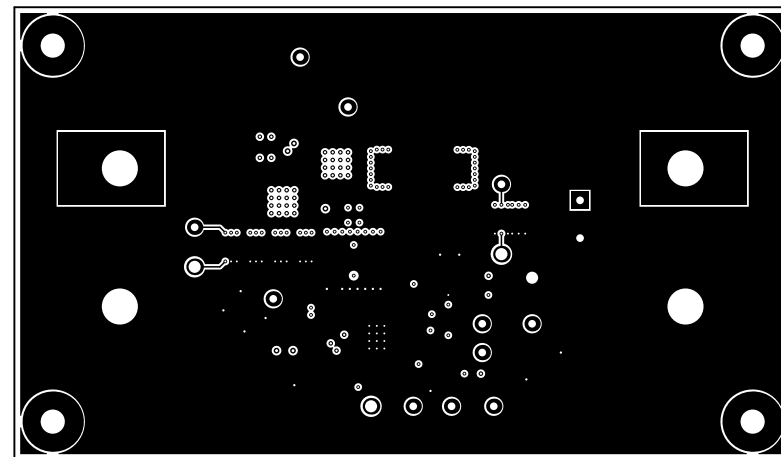
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20808	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 11/30/2017 6:37:51 PM	TEXAS INSTRUMENTS	



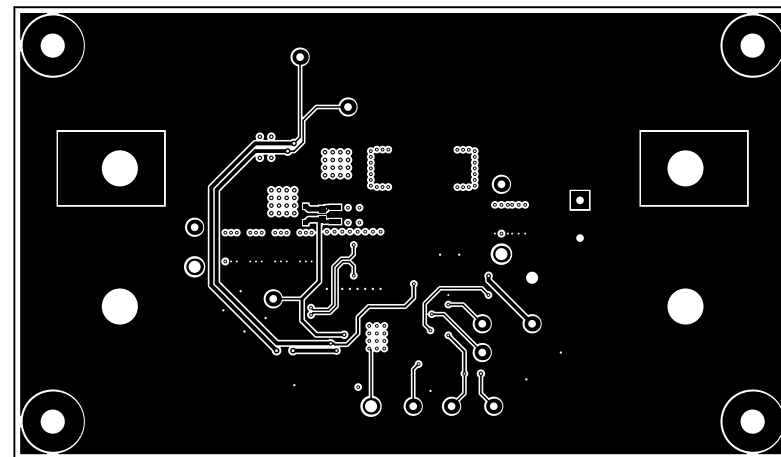
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20808	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 11/30/2017 6:37:52 PM	TEXAS INSTRUMENTS	



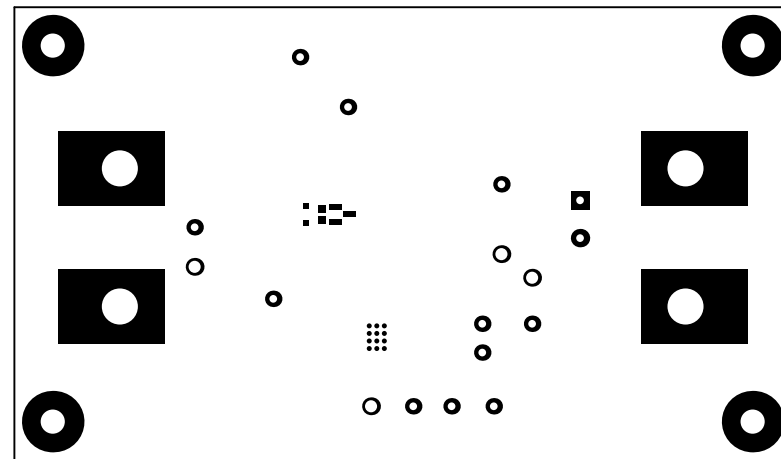
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20808	REV: A	SUN REV: Not In VersionControl
LAYER NAME = MidLayer1			
PLOT NAME = Signal Layer 1	GENERATED : 11/30/2017 6:37:52 PM	TEXAS INSTRUMENTS	



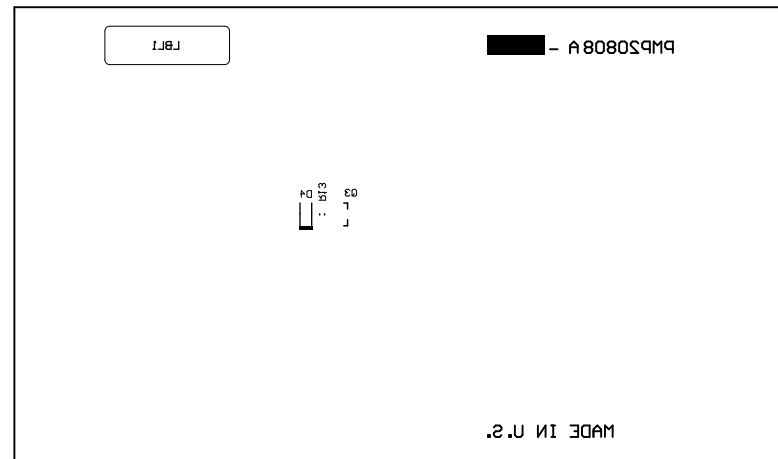
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20808	REV: A	SUN REV: Not In VersionControl
LAYER NAME = MidLayer2			
PLOT NAME = Signal Layer 2	GENERATED : 11/30/2017 6:37:53 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20808	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 11/30/2017 6:37:54 PM	TEXAS INSTRUMENTS	

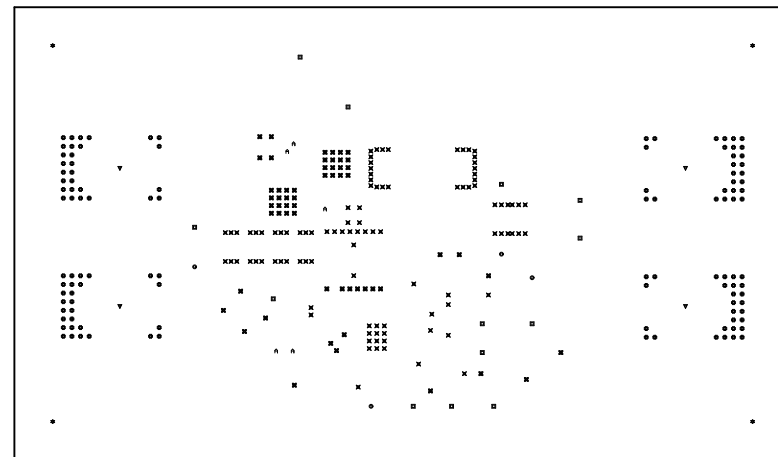


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20808	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 11/30/2017 6:37:55 PM	TEXAS INSTRUMENTS	



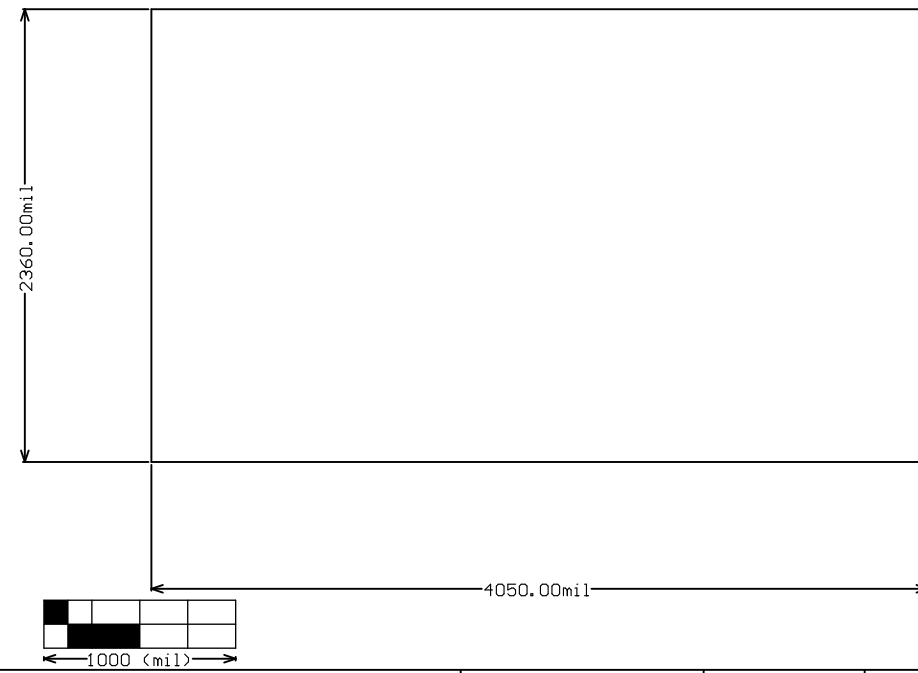
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20808	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 11/30/2017 6:37:55 PM	TEXAS INSTRUMENTS	





Symbol	Quantity	Finished Hole Size	Plated	Hole Type
✕	100	10.00mil (0.254mm)	PTH	Round
✕	58	12.00mil (0.305mm)	PTH	Round
⋈	5	15.00mil (0.381mm)	PTH	Round
⊕	112	16.00mil (0.406mm)	PTH	Round
⊕	13	40.00mil (1.016mm)	PTH	Round
⊕	4	63.00mil (1.600mm)	PTH	Round
⊕	4	125.98mil (3.200mm)	PTH	Round
▽	4	188.00mil (4.775mm)	PTH	Round
	300 Total			

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20808	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 11/30/2017 6:37:56 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20808	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 11/30/2017 6:37:58 PM	TEXAS INSTRUMENTS	

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